

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r m e s s a g e s	E r r o r r e c t i o n s
1	BRS	L1	383	(apply\$3 with (abrasive or slurry) with (pad or "polishing pad")) and (cmp or ("chemical mechanical" adj (polish\$3 or planariz\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 17:02			0
2	BRS	L2	110	1 and (EDTA or "ethylene diamine" or ammonia or "ethylene diamine tetra acetic")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 19:06			0
3	BRS	L3	51	2 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 19:08			0
4	BRS	L4	17	3 and @pd<=20010613	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 19:07			0
5	BRS	L5	74	1 and (EDTA or "ethylene diamine" or ammonia or "ethylene diamine tetra acetic") and (copper or Cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 19:07			0
6	BRS	L6	17	5 and @pd<=20010613	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 19:07			0
7	BRS	L7	8	6 and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/27 19:08			0